

REMARKS

Claim 1 calls for attaching ligands along a polymer bristle to form a semiconductor wafer cleaning brush.

The cited reference to Wang apparently teaches an ion exchange resin pad in the form of one or more sheets. See column 12, lines 37-44. Thus, at the least, he fails to teach attaching ligands along a polymer bristle, at least because he has no polymer bristle. Therefore, reconsideration of the rejection is respectfully requested.

Claim 2 is not specifically addressed, but it does not appear that the reference teaches attaching ligands using a hydrolysis reaction.

Claim 3 calls for attaching ligands along a polyvinyl alcohol polymer, which does not seem to occur in the cited reference, but the claim is not specifically addressed.

Claim 4 calls for using a coupling agent to attach the ligands. The office action does not specifically address the claim, but it does not appear that the reference talks about any coupling agent.

Claim 5 talks about attaching ligands to provide a hydrophilic property. While the rejection does not mention this claim specifically, it does not appear that such a property is pointed out in the rejection.

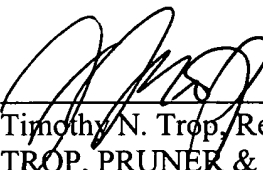
Claim 6 calls for attaching ligands to provide hydrophobic properties and, again, the comments with respect to claim 5 appear to apply to claim 6. The same analysis would apply to claims 7 and 8.

Likewise, reconsideration is requested with respect to claims 10, 11, and 12.

Reconsideration is requested on the same grounds with respect to claims 13-23.

Respectfully submitted,

Date: December 8, 2006



Timothy N. Trop, Reg. No. 28,994
TROP, PRUNER & HU, P.C.
1616 South Voss Road, Suite 750
Houston, TX 77057-2631
713/468-8880 [Phone]
713/468-8883 [Fax]
Attorneys for Intel Corporation